

# REMARKS

This is a Supplemental Amendment filed in the Request For Continued Examination (RCE) of the above-identified patent application filed by Certificate of Mailing dated May 6, 2003.

By the present amendment, claims 16-19 and 25 are pending in this application.

This amendment has been made to highlight the feature of the present invention directed to the adhesive bonding of solder balls (metal balls) to the electrodes of a device with a flux without reflowing the metal balls.

See arguments for patentability in the Remarks accompanying the Request For Continued Examination.

It is submitted that pending claims 16-19 and 25 are patentable.

CONCLUSION

An action on the merits is respectfully requested.

Respectfully submitted,

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